505859108 01/10/2020

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5906045

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
SHINJI IRIFUNE	12/27/2019
TOMOYA KANAI	12/27/2019
MASAKI TANAKA	12/24/2019
MINORU SUGIYAMA	12/16/2019
HIDENOBU MORISHIMA	12/16/2019
KAZUHIRO SATO	12/16/2019

## **RECEIVING PARTY DATA**

SHIN-ETSU CHEMICAL CO., LTD.
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KURASHIKI BOSEKI KABUSHIKI KAISHA
7-1, HOMMACHI
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JAPAN

# **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16630316

# **CORRESPONDENCE DATA**

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REEL: 051482 FRAME: 0562

PATENT

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ATTORNEY DOCKET NUMBER:	10873.2715USWO
NAME OF SUBMITTER:	DOUGLAS P. MUELLER
SIGNATURE:	/dpmueller/
DATE SIGNED:	01/10/2020
Total Attachments: 3	
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PATENT REEL: 051482 FRAME: 0563 Docket No.

#### ASSIGNMENT OF PATENT APPLICATION

### WHEREAS,

- 1. <u>Shinji IRIFUNE</u> residing at <u>c/o SHIN-ETSU CHEMICAL CO., LTD., Silicone-Electronics Materials Research Center, 1-10, Hitomi, Matsuida-machi, Annaka-shi, Gunma 379-0224 Japan and a citizen of Japan</u>
- 2. <u>Tomoya KANAI</u> residing at <u>c/o SHIN-ETSU CHEMICAL CO., LTD., Silicone-Electronics Materials Research Center, 1-10, Hitomi, Matsuida-machi, Annaka-shi, Gunma 379-0224 Japan</u> and a citizen of <u>Japan</u>
- 3. <u>Masaki TANAKA</u> residing at <u>c/o SHIN-ETSU CHEMICAL CO., LTD., 6-1, Ohtemachi 2-chome, Chiyoda-ku, Tokyo 100-0004 Japan</u> and a citizen of <u>Japan</u>
- 4. Minoru SUGIYAMA residing at c/o KURASHIKI BOSEKI KABUSHIKI KAISHA TECHNICAL RESEARCH LABORATORY, 14-30, Shimokida-cho, Neyagawa-shi, Osaka 572-0823 Japan and a citizen of Japan
- 5. <u>Hidenobu MORISHIMA</u> residing at <u>c/o KURASHIKI BOSEKI KABUSHIKI KAISHA TECHNICAL RESEARCH LABORATORY</u>, 14-30, Shimokida-cho, Neyagawa-shi, Osaka 572-0823 Japan and a citizen of <u>Japan</u>
- 6. <u>Kazuhiro SATO</u> residing at <u>c/o KURASHIKI BOSEKI KABUSHIKI KAISHA</u>
  <u>TECHNICAL RESEARCH LABORATORY</u>, 14-30, Shimokida-cho, Neyagawa-shi,
  Osaka 572-0823 Japan and a citizen of <u>Japan</u>

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on , entitled <a href="FUNCTIONAL-AGENT-CONTAINING FIBER AND METHOD FOR MANUFACTURING SAME">FUNCTIONAL-AGENT-CONTAINING FIBER AND METHOD FOR MANUFACTURING SAME</a>, and which has been given application serial number

and

WHEREAS,

<u>SHIN-ETSU CHEMICAL CO., LTD.</u> (hereinafter "ASSIGNEE") a corporation organized under the laws of <u>Japan</u> and having an office and place of business at <u>6-1</u>, <u>Ohtemachi 2-chome, Chiyoda-ku, Tokyo 100-0004, JAPAN</u>; and

KURASHIKI BOSEKI KABUSHIKI KAISHA (hereinafter "ASSIGNEE") a corporation organized under the laws of <u>Japan</u> and having an office and place of business at <u>7-1</u>, <u>Hommachi, Kurashiki-shi, Okayama 710-0054 Japan</u>

wish to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

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NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEEs, their successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the ASSIGNEEs of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEEs) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEEs, their successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEEs, their successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEEs, their successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Tomoya Kanai Signature: Tomoya KANAI

<u>December 27,</u> 2019 Date

December 24, 2019 Date

Minoru SUGIYAMA

Signature: Minoru SUGIYAMA

Li denobu MORI 92 MA

Signature: Hidenobu MORISHIMA

La denobu MORISHIMA

Date

La denobu MORISHIMA

Date